

**BOND FINGER ON VIA SUBSTRATE, PROCESS OF MAKING SAME,
PACKAGE MADE THEREBY, AND METHOD OF ASSEMBLING SAME**

ABSTRACT OF THE DISCLOSURE

5 A wire-bonding substrate is disclosed. The wire-bonding substrate includes a first wire-bond pad and a first via that is disposed directly below the first wire-bond pad in the in the wire-bonding substrate. A package is also disclosed that includes a die that is coupled to the first wire-bonding pad. The package can include a larger substrate that is coupled to the wire-bonding substrate through an
10 electrical connection such as a solder ball. A process of forming the wire-bonding substrate is also disclosed. The process includes via formation to stop on the wire-bond pad. A method of assembling a microelectronic package is also disclosed that includes coupling the die to the wire-bond pad. A computing system is also disclosed that includes the wire-bonding substrate.